

Silicon PNP Epitaxial

REJ03G0661-0200 (Previous ADE-208-1036) Rev.2.00 Aug.10.2005

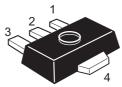
Application

• Low frequency power amplifier

• Complementary pair with 2SD1418

Outline

RENESAS Package code: PLZZ0004CA-A (Package name: UPAK $^{\textcircled{R}})$



1. Base 2. Collector 3. Emitter

4. Collector (Flange)

*UPAK is a trademark of Renesas Technology Corp.

Absolute Maximum Ratings

			(Ta = 25°C)
Item	Symbol	Ratings	Unit
Collector to base voltage	V _{CBO}	-120	V
Collector to emitter voltage	V _{CEO}	-80	V
Emitter to base voltage	V _{EBO}	-5	V
Collector current	I _C	-1	A
Collector peak current	i _{C(peak)} * ¹	-2	A
Collector power dissipation	Pc*2	1	W
Junction temperature	Tj	150	°C
Storage temperature	Tstg	-55 to +150	°C

Notes: 1. $PW \le 10 \text{ ms}$, $Duty cycle \le 20\%$

2. Value on the alumina ceramic board (12.5 \times 20 \times 0.7 mm)

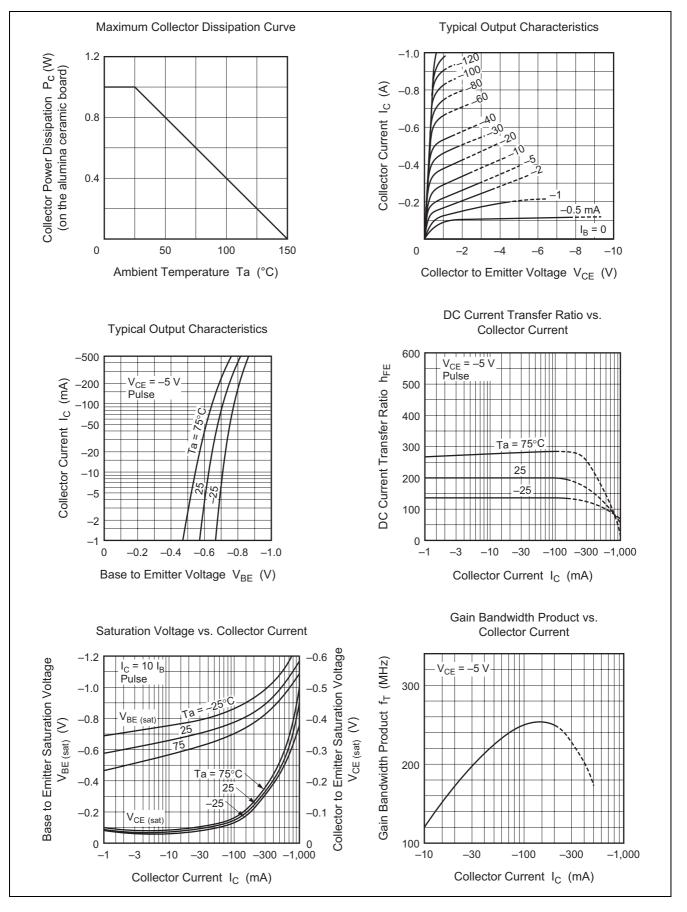


Electrical Characteristics

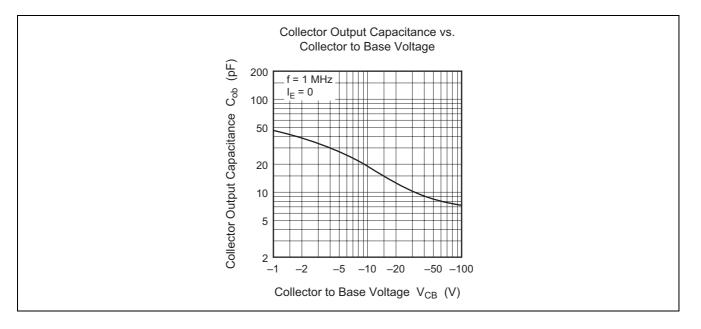
						(Ta = 25°C)
ltem	Symbol	Min	Тур	Max	Unit	Test conditions
Collector to base breakdown voltage	V _{(BR)CBO}	-120	—		V	$I_{\rm C} = -10 \ \mu A, \ I_{\rm E} = 0$
Collector to emitter breakdown voltage	V _{(BR)CEO}	-80	—		V	$I_{C} = -1 \text{ mA}, R_{BE} = \infty$
Emitter to base breakdown voltage	V _{(BR)EBO}	-5	—	_	V	$I_E = -10 \ \mu A, \ I_C = 0$
Collector cutoff current	I _{CBO}	—	—	-10	μA	$V_{CB} = -100 \text{ V}, I_E = 0$
DC current transfer ratio	h _{FE1}	100	—	200		$V_{CE} = -5 \text{ V}, I_C = -150 \text{ mA}$
	h _{FE2}	30	—	_		$V_{CE} = -5 V,$
						I _C = -500 mA (Pulse test)
Collector to emitter saturation voltage	V _{CE(sat)}	_	_	-1	V	$I_{\rm C} = -500 \text{ mA},$
						$I_B = -50 \text{ mA}$ (Pulse test)
Base to emitter voltage	V _{BE}	—	—	-0.9	V	$V_{CE} = -5 \text{ V}, I_C = -150 \text{ mA}$
Gain bandwidth product	f⊤	_	140		MHz	$V_{CE} = -5 \text{ V}, \text{ I}_{C} = -150 \text{ mA}$
Collector output capacitance	Cob	_	20		pF	$V_{CB} = -10 \text{ V}, I_E = 0,$
						f = 1 MHz



Main Characteristics

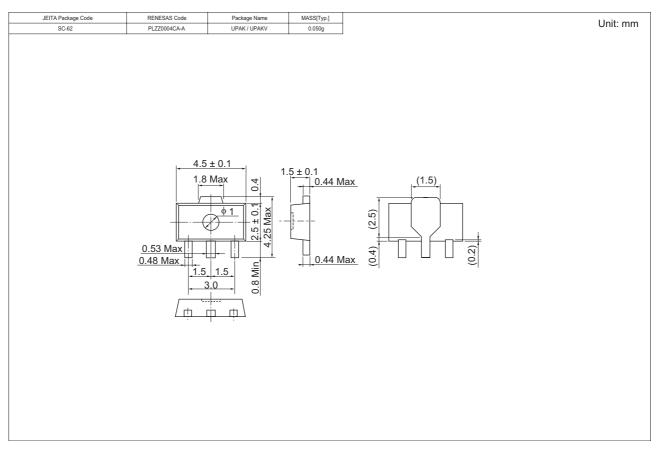








Package Dimensions



Ordering Information

Part Name	Quantity	Shipping Container
2SB1025DJTL-E	1000	φ 178 mm Reel, 12 mm Emboss Taping

Note: For some grades, production may be terminated. Please contact the Renesas sales office to check the state of production before ordering the product.



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